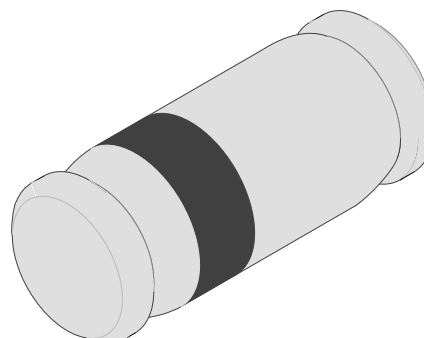


# Schottky Barrier Diode

## Features

- Integrated protection ring against static discharge
- Very low forward voltage



94 9371

## Applications

Applications where a very low forward voltage is required

## Absolute Maximum Ratings

 $T_j = 25^{\circ}\text{C}$ 

Parameter	Test Conditions	Type	Symbol	Value	Unit
Reverse voltage			$V_R$	50	V
Peak forward surge current	$t_p=10\text{ ms}$		$I_{FSM}$	5	A
Repetitive peak forward current	$t_p \leq 1\text{ s}$		$I_{FRM}$	500	mA
Forward current			$I_F$	200	mA
Average forward current			$I_{FAV}$	200	mA
Junction temperature			$T_j$	125	$^{\circ}\text{C}$
Storage temperature range			$T_{stg}$	-65...+150	$^{\circ}\text{C}$

## Maximum Thermal Resistance

 $T_j = 25^{\circ}\text{C}$ 

Parameter	Test Conditions	Symbol	Value	Unit
Junction ambient	on PC board 50mmx50mmx1.6mm	$R_{thJA}$	320	K/W

## Electrical Characteristics

 $T_j = 25^{\circ}\text{C}$ 

Parameter	Test Conditions	Type	Symbol	Min	Typ	Max	Unit
Forward voltage	$I_F=0.1\text{ mA}$		$V_F$			300	mV
	$I_F=1\text{ mA}$		$V_F$			380	mV
	$I_F=10\text{ mA}$		$V_F$			450	mV
	$I_F=30\text{ mA}$		$V_F$			600	mV
	$I_F=100\text{ mA}$		$V_F$			900	mV
Reverse current	$V_R=40\text{ V}$		$I_R$			5	$\mu\text{A}$
Diode capacitance	$V_R=1\text{ V}, f=1\text{ MHz}$		$C_D$			8	pF

### Characteristics ( $T_j = 25^\circ\text{C}$ unless otherwise specified)

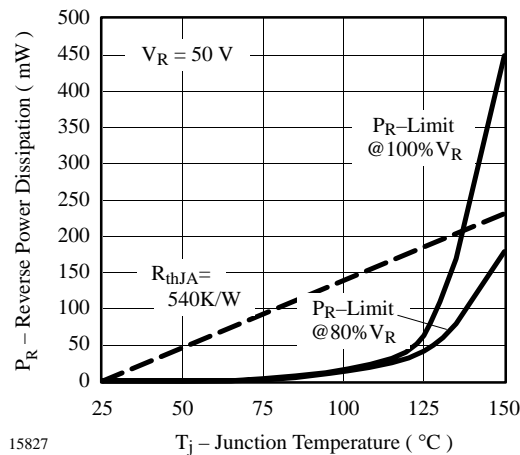


Figure 1. Max. Reverse Power Dissipation vs. Junction Temperature

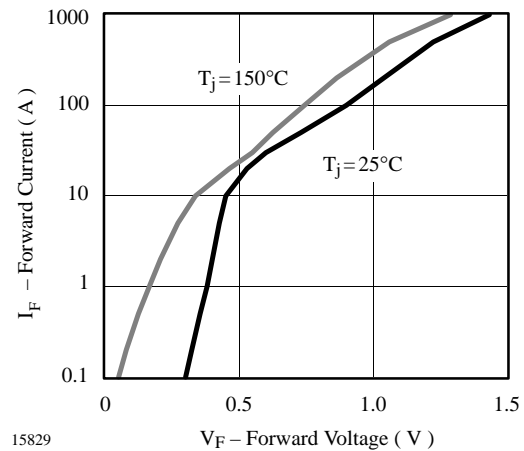


Figure 3. Forward Current vs. Forward Voltage

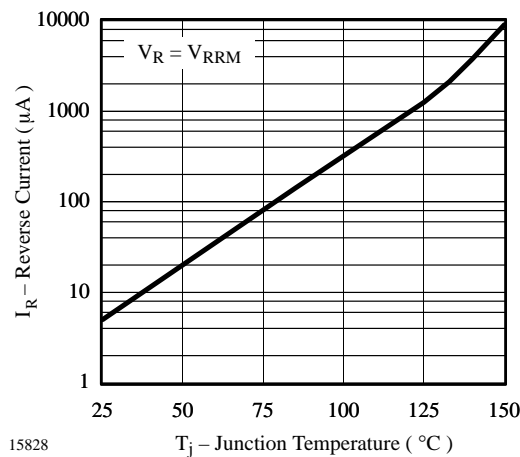


Figure 2. Reverse Current vs. Junction Temperature

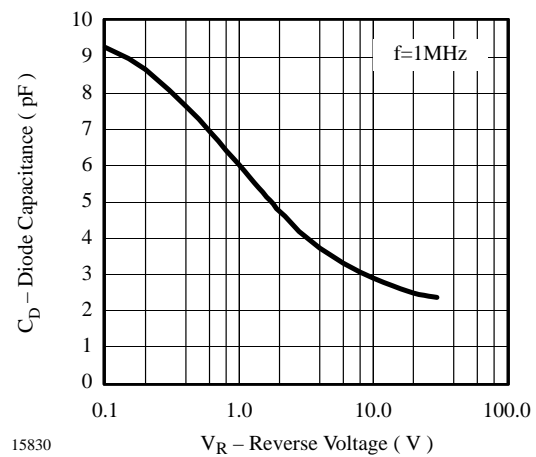
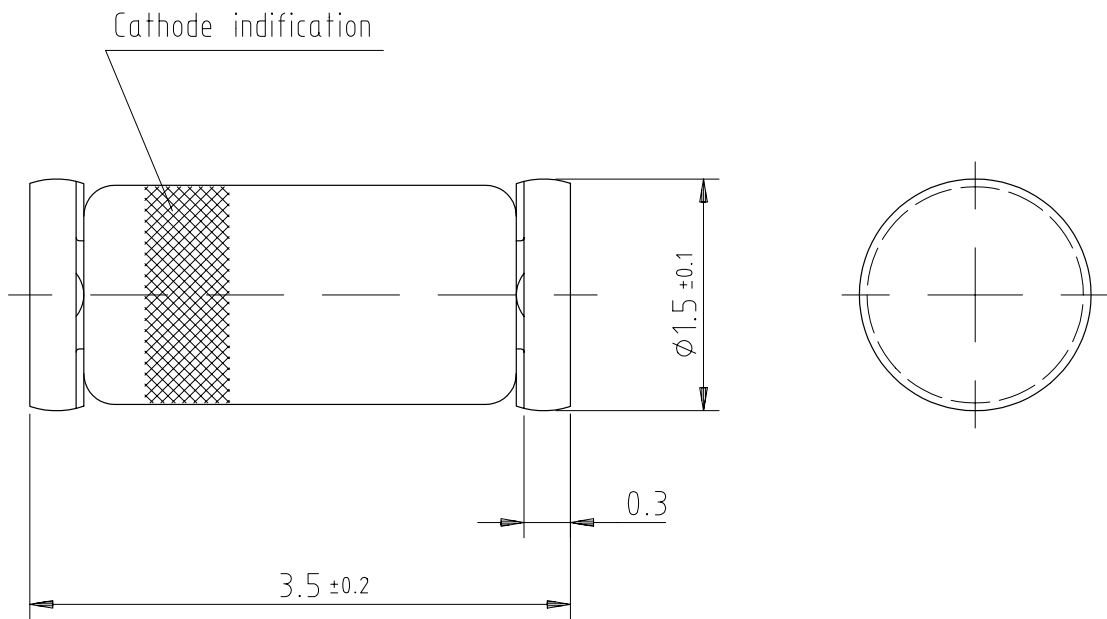


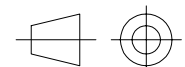
Figure 4. Diode Capacitance vs. Reverse Voltage

**Dimensions in mm**



Glass case  
Mini MELF / SOD 80  
JEDEC DO 213 AA

96 12070



technical drawings  
according to DIN  
specifications

## **Ozone Depleting Substances Policy Statement**

It is the policy of **Vishay Semiconductor GmbH** to

1. Meet all present and future national and international statutory requirements.
2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems  
with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

**Vishay Semiconductor GmbH** has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively
2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA
3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

**Vishay Semiconductor GmbH** can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

**We reserve the right to make changes to improve technical design and may do so without further notice.**

Parameters can vary in different applications. All operating parameters must be validated for each customer application by the customer. Should the buyer use Vishay-Telefunken products for any unintended or unauthorized application, the buyer shall indemnify Vishay-Telefunken against all claims, costs, damages, and expenses, arising out of, directly or indirectly, any claim of personal damage, injury or death associated with such unintended or unauthorized use.

Vishay Semiconductor GmbH, P.O.B. 3535, D-74025 Heilbronn, Germany  
Telephone: 49 (0) 7131 67 2831, Fax number: 49 (0) 7131 67 2423